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Kind regards,

Team Nexperia

PMBT3904MB

40 V, 200 mA NPN switching transistor

Rev. 1 — 7 March 2012 **Product data sheet**

1. Product profile

1.1 General description

NPN single switching transistor in a leadless ultra small SOT883B Surface-Mounted Device (SMD) plastic package.

PNP complement: PMBT3906MB.

1.2 Features and benefits

- Single general-purpose switching transistor
- AEC-Q101 qualified
- Ultra small SMD plastic package
- Board-space reduction
- Low package height of 0.37 mm

1.3 Applications

- General-purpose switching and amplification
- Mobile applications

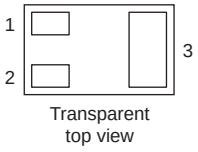
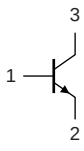
1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	40	V
I_C	collector current		-	-	200	mA
h_{FE}	DC current gain	V_{CE} = 1 V; I_C = 10 mA	100	180	300	

2. Pinning information

Table 2. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	base	 Transparent top view	 sym021
2	emitter		
3	collector		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMBT3904MB		leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.37 mm	SOT883B

4. Marking

Table 4. Marking codes

Type number	Marking code[1]
PMBT3904MB	0100 0111

[1] For SOT883B binary marking code description see Figure 1.

4.1 Binary marking code description

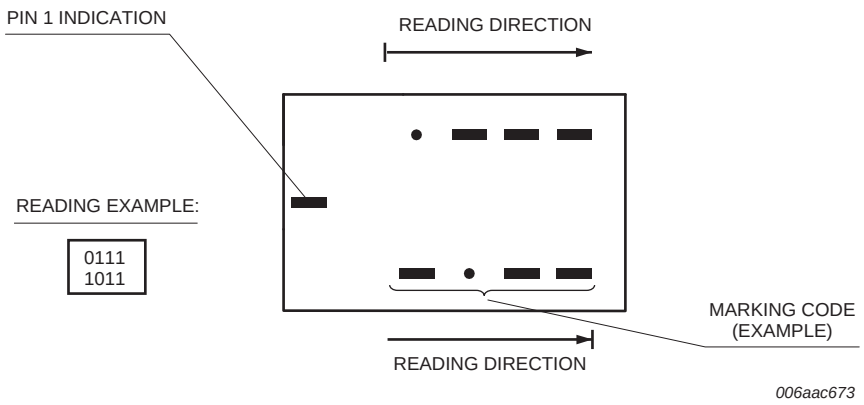


Fig 1. SOT883B binary marking code description

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	60	V
V_{CEO}	collector-emitter voltage	open base		-	40	V
V_{EBO}	emitter-base voltage	open collector		-	6	V
I_C	collector current			-	200	mA
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	200	mA
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms		-	100	mA
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1][2]	-	250	mW
			[1][3]	-	590	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			−55	+150	°C
T_{stg}	storage temperature			−65	+150	°C

[1] Reflow soldering is the only recommended soldering method.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.

6. Thermal characteristics

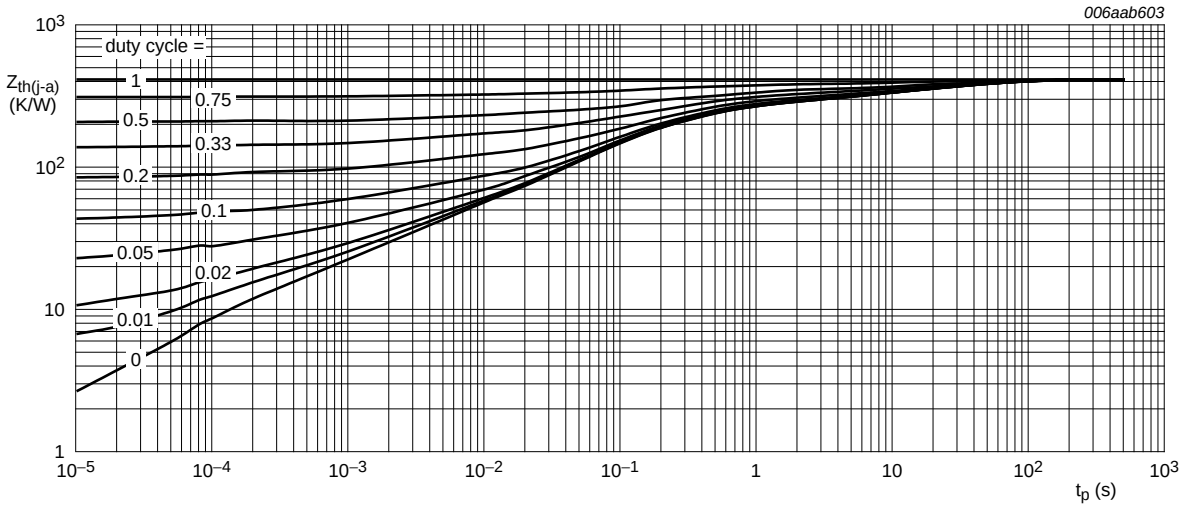
Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2]	-	-	500	K/W
			[1][3]	-	-	212	K/W

[1] Reflow soldering is the only recommended soldering method.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.



FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

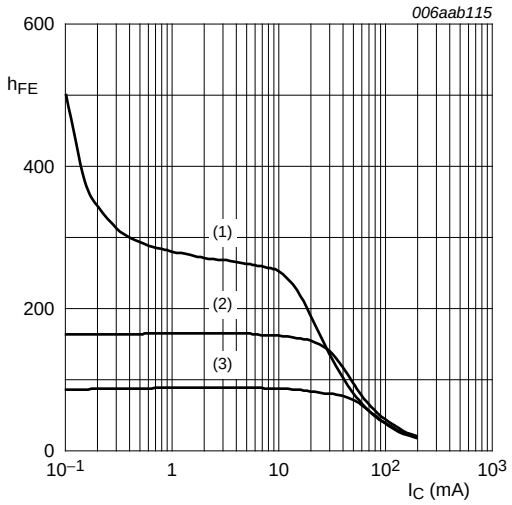
7. Characteristics

Table 7. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = 30 V; I_E = 0 A		-	-	50	nA
I_{EBO}	emitter-base cut-off current	V_{EB} = 6 V; I_C = 0 A		-	-	50	nA
h_{FE}	DC current gain	V_{CE} = 1 V					
		I_C = 0.1 mA		60	180	-	
		I_C = 1 mA		80	180	-	
		I_C = 10 mA		100	180	300	
		I_C = 50 mA		60	105	-	
		I_C = 100 mA	[1]	30	50	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = 10 mA; I_B = 1 mA		-	75	200	mV
		I_C = 50 mA; I_B = 5 mA		-	120	300	mV
V_{BEsat}	base-emitter saturation voltage	I_C = 10 mA; I_B = 1 mA		650	750	850	mV
		I_C = 50 mA; I_B = 5 mA		-	850	950	mV
t_d	delay time	V_{CC} = 3 V; I_C = 10 mA; I_{Bon} = 1 mA; I_{Boff} = −1 mA		-	-	35	ns
t_r	rise time			-	-	35	ns
t_{on}	turn-on time			-	-	70	ns
t_s	storage time			-	-	200	ns
t_f	fall time			-	-	50	ns
t_{off}	turn-off time			-	-	250	ns
C_c	collector capacitance	V_{CB} = 5 V; I_E = i_e = 0 A; f = 1 MHz		-	-	4	pF
C_e	emitter capacitance	V_{EB} = 500 mV; I_C = i_c = 0 A; f = 1 MHz		-	-	8	pF
f_T	transition frequency	V_{CE} = 20 V; I_C = 10 mA; f = 100 MHz		300	-	-	MHz
NF	noise figure	V_{CE} = 5 V; I_C = 100 μA; R_S = 1 kΩ; f = 10 Hz to 15.7 kHz		-	-	5	dB

[1] Pulse test: $t_p \leq 300$ μs; $\delta \leq 0.02$.



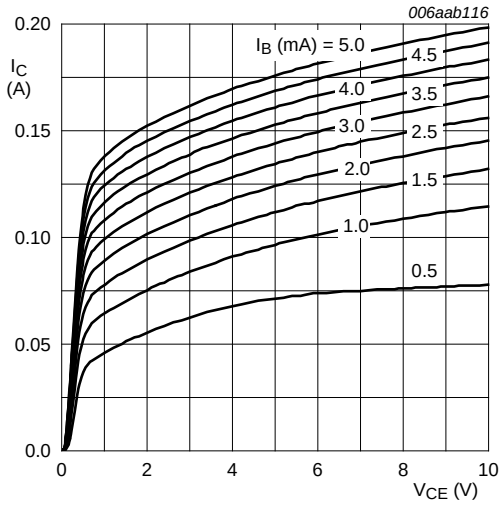
V_{CE} = 1 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

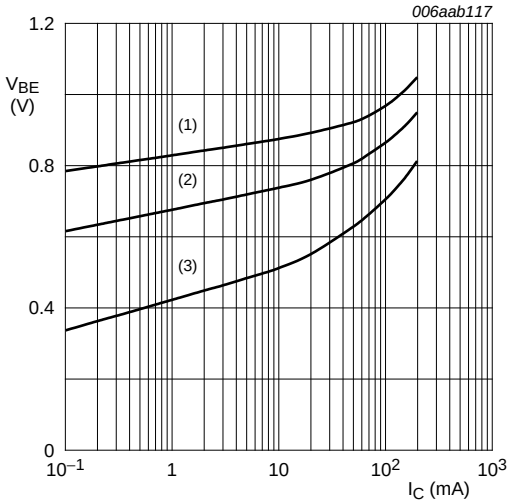
(3) T_{amb} = −55 °C

Fig 3. DC current gain as a function of collector current; typical values



T_{amb} = 25 °C

Fig 4. Collector current as a function of collector-emitter voltage; typical values



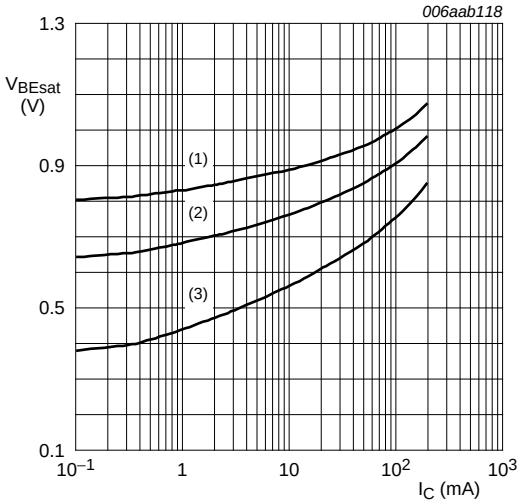
V_{CE} = 1 V

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 5. Base-emitter voltage as a function of collector current; typical values



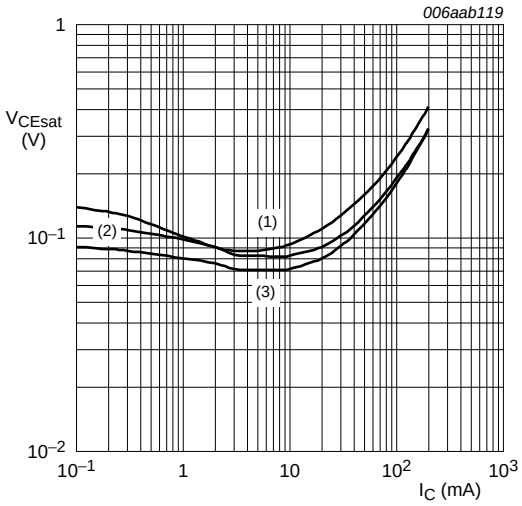
I_C/I_B = 10

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 6. Base-emitter saturation voltage as a function of collector current; typical values



I_C/I_B = 10

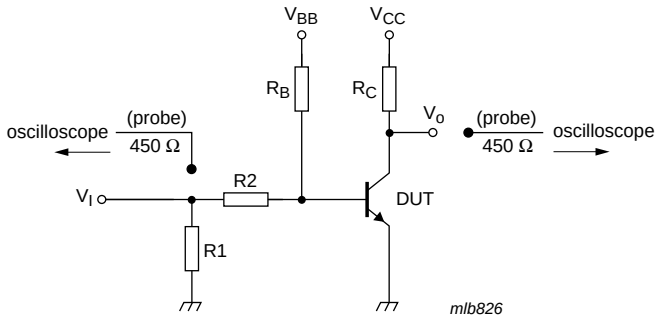
(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 7. Collector-emitter saturation voltage as a function of collector current; typical values

8. Test information



V_I = 5 V; t = 600 μs; t_p = 10 μs; $t_r = t_f \leq 3$ ns

R1 = 56 Ω; R2 = 2.5 kΩ; R_B = 3.9 kΩ; R_C = 270 Ω

V_{BB} = −1.9 V; V_{CC} = 3 V

Oscilloscope: input impedance Z_i = 50 Ω

Fig 8. Test circuit for switching times

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline

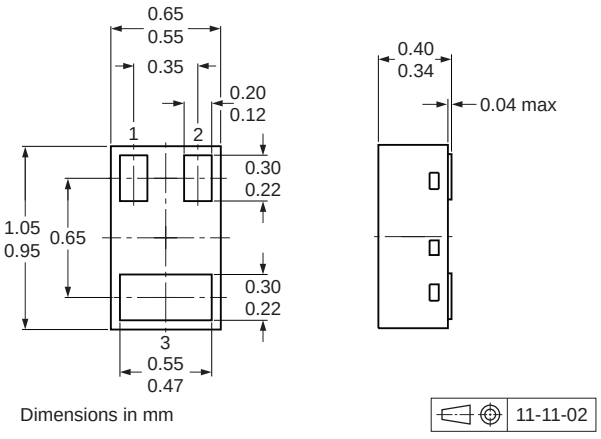


Fig 9. Package outline SOT883B

10. Packing information

Table 8. Packing methods

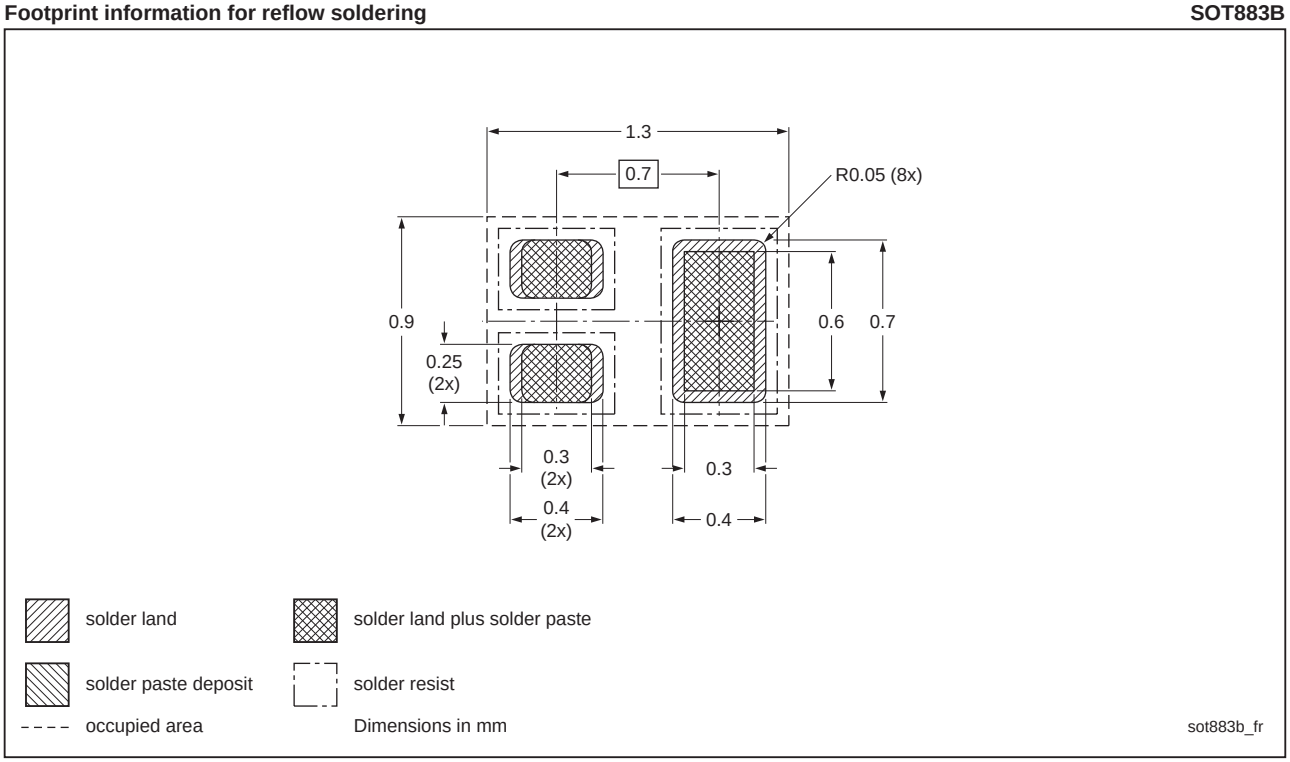
The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number	Package	Description	Packing quantity
			10000
PMBT3904MB	SOT883B	2 mm pitch, 8 mm tape and reel	-315

[1] For further information and the availability of packing methods, see Section 14.

11. Soldering

Footprint information for reflow soldering **SOT883B**



Reflow soldering is the only recommended soldering method.

Fig 10. Reflow soldering footprint SOT883B

12. Revision history

Table 9. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMBT3904MB v.1	20120307	Product data sheet	-	-

13. Legal information

13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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15. Contents

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